SN74LVCH16374A
16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP
WITH 3-STATE OUTPUTS

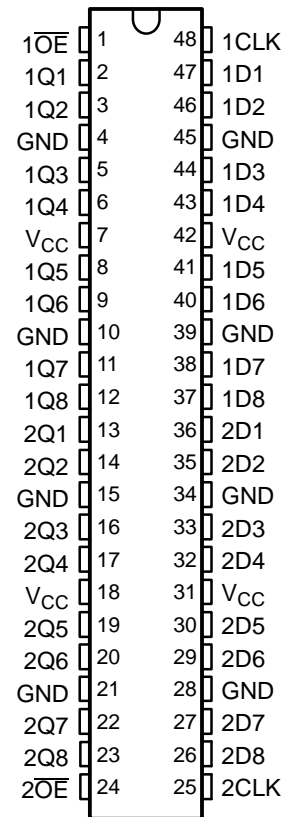SCAS757A−DECEMBER 2003−REVISED OCTOBER 2005

FEATURES

- **Member of the Texas Instruments Widebus™ Family**
- **Operates From 1.65 V to 3.6 V**
- **Inputs Accept Voltages to 5.5 V**
- **Max t_{pd} of 4.5 ns at 3.3 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Supports Mixed-Mode Signal Operation on All Ports (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **1000-V Charged-Device Model (C101)**

DESCRIPTION/ORDERING INFORMATION

This 16-bit edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V V_{CC} operation.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)

1$\overline{OE}$	1	48	1CLK
1Q1	2	47	1D1
1Q2	3	46	1D2
GND	4	45	GND
1Q3	5	44	1D3
1Q4	6	43	1D4
V_{CC}	7	42	V_{CC}
1Q5	8	41	1D5
1Q6	9	40	1D6
GND	10	39	GND
1Q7	11	38	1D7
1Q8	12	37	1D8
2Q1	13	36	2D1
2Q2	14	35	2D2
GND	15	34	GND
2Q3	16	33	2D3
2Q4	17	32	2D4
V_{CC}	18	31	V_{CC}
2Q5	19	30	2D5
2Q6	20	29	2D6
GND	21	28	GND
2Q7	22	27	2D7
2Q8	23	26	2D8
2$\overline{OE}$	24	25	2CLK

ORDERING INFORMATION

T_A	PACKAGE[1]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	FBGA – GRD	Tape and reel	SN74LVCH16374AGRDR	LDH374A
	FBGA – ZRD (Pb-free)		SN74LVCH16374AZRDR	
	SSOP – DL	Tube	SN74LVCH16374ADL	LVCH16374A
			74LVCH16374ADLG4	
		Tape and reel	SN74LVCH16374ADL	
			74LVCH16374ADLRG4	
	TSSOP – DGG	Tape and reel	SN74LVCH16374ADGGR	LVCH16374A
			74LVCH16374ADGGRG4	
	TVSOP – DGV	Tape and reel	SN74LVCH16374ADGVR	LDH374A
			74LVCH16374ADGVRE4	
	VFBGA – GQL	Tape and reel	SN74LVCH16374AGQLR	LDH374A
	VFBGA – ZQL (Pb-free)		SN74LVCH16374AZQLR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

A buffered output-enable ($\overline{\text{OE}}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{\text{OE}}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

The SN74LVCH16374A is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. It can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

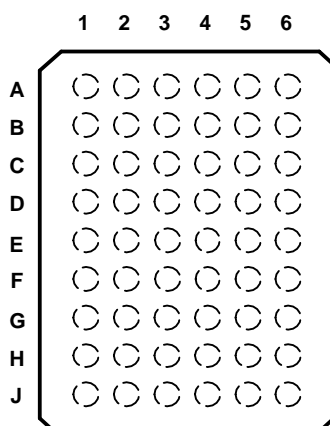**GQL OR ZQL PACKAGE**
(TOP VIEW)
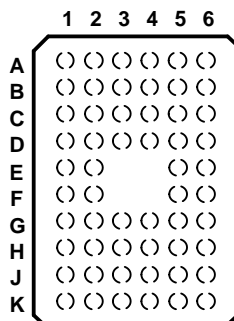
TERMINAL ASSIGNMENTS[1]
(56-Ball GQL/ZQL Package)

	1	2	3	4	5	6
A	1$\overline{\text{OE}}$	NC	NC	NC	NC	1CLK
B	1Q2	1Q1	GND	GND	1D1	1D2
C	1Q4	1Q3	V_{CC}	V_{CC}	1D3	1D4
D	1Q6	1Q5	GND	GND	1D5	1D6
E	1Q8	1Q7			1D7	1D8
F	2Q1	2Q2			2D2	2D1
G	2Q3	2Q4	GND	GND	2D4	2D3
H	2Q5	2Q6	V_{CC}	V_{CC}	2D6	2D5
J	2Q7	2Q8	GND	GND	2D8	2D7
K	2$\overline{\text{OE}}$	NC	NC	NC	NC	2CLK

(1) NC – No internal connection

GRD OR ZRD PACKAGE
(TOP VIEW)



TERMINAL ASSIGNMENTS[1]
(54-Ball GRD/ZRD Package)

	1	2	3	4	5	6
A	1Q1	NC	1$\overline{\text{OE}}$	1CLK	NC	1D1
B	1Q3	1Q2	NC	NC	1D2	1D3
C	1Q5	1Q4	V_{CC}	V_{CC}	1D4	1D5
D	1Q7	1Q6	GND	GND	1D6	1D7
E	2Q1	1Q8	GND	GND	1D8	2D1
F	2Q3	2Q2	GND	GND	2D2	2D3
G	2Q5	2Q4	V_{CC}	V_{CC}	2D4	2D5
H	2Q7	2Q6	NC	NC	2D6	2D7
J	2Q8	NC	2$\overline{\text{OE}}$	2CLK	NC	2D8

(1) NC – No internal connection

**FUNCTION TABLE
(EACH FLIP-FLOP)**

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)

To Seven Other Channels   To Seven Other Channels
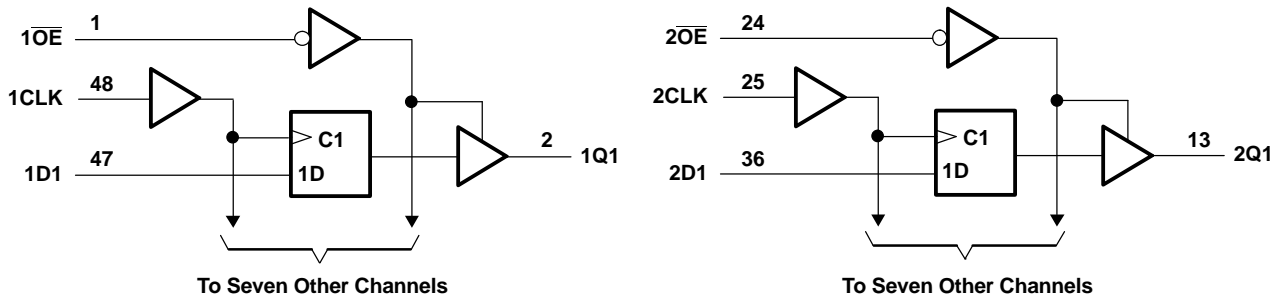
Pin numbers shown are for the DGG, DGV, and DL packages.

Absolute Maximum Ratings[1]

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		−0.5	6.5	V
V_I	Input voltage range[2]		−0.5	6.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state[2]		−0.5	6.5	V
V_O	Voltage range applied to any output in the high or low state[2][3]		−0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	$V_I < 0$		−50	mA
I_{OK}	Output clamp current	$V_O < 0$		−50	mA
I_O	Continuous output current			±50	mA
	Continuous current through each V_{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance[4]	DGG package		70	°C/W
		DGV package		58	
		DL package		63	
		GQL/ZQL package		42	
		GRD/ZRD package		36	
T_{stg}	Storage temperature range		−65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The value of V_{CC} is provided in the recommended operating conditions table.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

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Recommended Operating Conditions[1]

			MIN	MAX	UNIT
V_{CC}	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
V_{IH}	High-level input voltage	V_{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		V
		V_{CC} = 2.3 V to 2.7 V	1.7		
		V_{CC} = 2.7 V to 3.6 V	2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	V
		V_{CC} = 2.3 V to 2.7 V		0.7	
		V_{CC} = 2.7 V to 3.6 V		0.8	
V_I	Input voltage		0	5.5	V
V_O	Output voltage	High or low state	0	V_{CC}	V
		High-impedance state	0	5.5	
I_{OH}	High-level output current	V_{CC} = 1.65 V		−4	mA
		V_{CC} = 2.3 V		−8	
		V_{CC} = 2.7 V		−12	
		V_{CC} = 3 V		−24	
I_{OL}	Low-level output current	V_{CC} = 1.65 V		4	mA
		V_{CC} = 2.3 V		8	
		V_{CC} = 2.7 V		12	
		V_{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature		−40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	MIN	TYP[1]	MAX	UNIT
V_{OH}	$I_{OH} = -100\ \mu A$		1.65 V to 3.6 V	$V_{CC} - 0.2$			V
	$I_{OH} = -4\ mA$		1.65 V	1.2			
	$I_{OH} = -8\ mA$		2.3 V	1.7			
	$I_{OH} = -12\ mA$		2.7 V	2.2			
			3 V	2.4			
	$I_{OH} = -24\ mA$		3 V	2.2			
V_{OL}	$I_{OL} = 100\ \mu A$		1.65 V to 3.6 V			0.2	V
	$I_{OL} = 4\ mA$		1.65 V			0.45	
	$I_{OL} = 8\ mA$		2.3 V			0.7	
	$I_{OL} = 12\ mA$		2.7 V			0.4	
	$I_{OL} = 24\ mA$		3 V			0.55	
I_I	$V_I = 0$ to 5.5 V		3.6 V			±5	μA
$I_{I(hold)}$	$V_I = 0.58\ V$		1.65 V		(2)		μA
	$V_I = 1.07\ V$				(2)		
	$V_I = 0.7\ V$		2.3 V		45		
	$V_I = 1.7\ V$				−45		
	$V_I = 0.8\ V$		3 V		75		
	$V_I = 2\ V$				−75		
	$V_I = 0$ to 3.6 V [3]		3.6 V			±500	
I_{off}	V_I or $V_O = 5.5$ V		0			±10	μA
I_{OZ}	$V_O = 0$ to 5.5 V		3.6 V			±10	μA
I_{CC}	$V_I = V_{CC}$ or GND	$I_O = 0$	3.6 V			20	μA
	$3.6\ V \le V_I \le 5.5\ V$ [4]					20	
ΔI_{CC}	One input at $V_{CC} - 0.6$ V, Other inputs at V_{CC} or GND		2.7 V to 3.6 V			500	μA
C_i	$V_I = V_{CC}$ or GND		3.3 V		5		pF
C_o	$V_O = V_{CC}$ or GND		3.3 V		6.5		pF

(1) All typical values are at $V_{CC} = 3.3$ V, $T_A = 25°C$.
(2) This information was not available at the time of publication.
(3) This is the bus-hold maximum dynamic current required to switch the input from one state to another.
(4) This applies in the disabled state only.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		$V_{CC} = 1.8$ V ± 0.15 V		$V_{CC} = 2.5$ V ± 0.2 V		$V_{CC} = 2.7$ V		$V_{CC} = 3.3$ V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		(1)		(1)		150		150	MHz
t_w	Pulse duration, CLK high or low	(1)		(1)		3.3		3.3		ns
t_{su}	Setup time, data before CLK↑	(1)		(1)		1.9		1.9		ns
t_h	Hold time, data after CLK↑	(1)		(1)		1.1		1.1		ns

(1) This information was not available at the time of publication.

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Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 1.8 V ± 0.15 V		V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			(1)		(1)		150		150		MHz
t_{pd}	CLK	Q	(1)	(1)	(1)	(1)		4.9	1.5	4.5	ns
t_{en}	$\overline{OE}$	Q	(1)	(1)	(1)	(1)		5.3	1.5	4.6	ns
t_{dis}	$\overline{OE}$	Q	(1)	(1)	(1)	(1)		6.1	1.5	5.5	ns
$t_{sk(o)}$										1	ns

(1)   This information was not available at the time of publication.

Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC} = 1.8 V TYP	V_{CC} = 2.5 V TYP	V_{CC} = 3.3 V TYP	UNIT
C_{pd} Power dissipation capacitance per flip-flop	Outputs enabled	f = 10 MHz	(1)	(1)	58	pF
	Outputs disabled		(1)	(1)	24	

(1)   This information was not available at the time of publication.
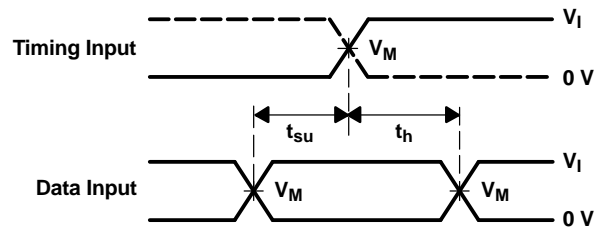
PARAMETER MEASUREMENT INFORMATION
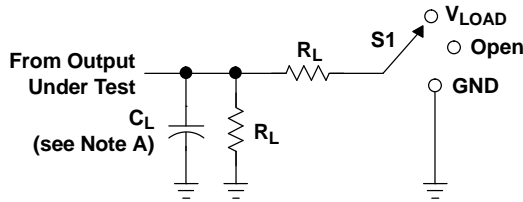
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

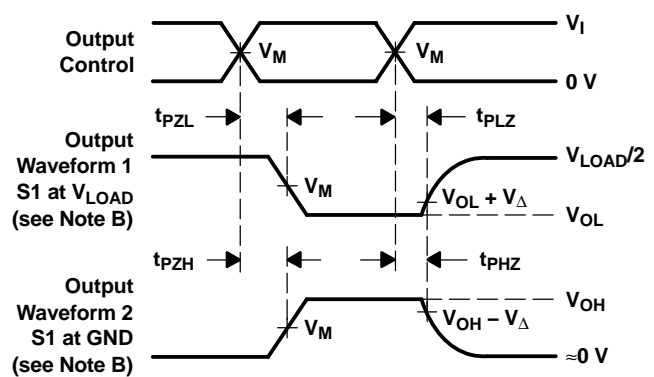| V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
1.8 V $\pm$ 0.15 V	V_{CC}	$\leq$2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 kΩ	0.15 V
2.5 V $\pm$ 0.2 V	V_{CC}	$\leq$2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq$2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	$\leq$2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
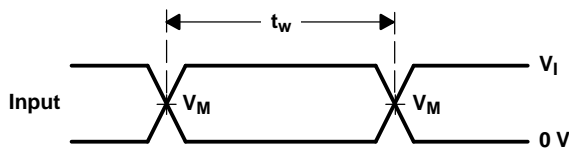
VOLTAGE WAVEFORMS
PULSE DURATION

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES
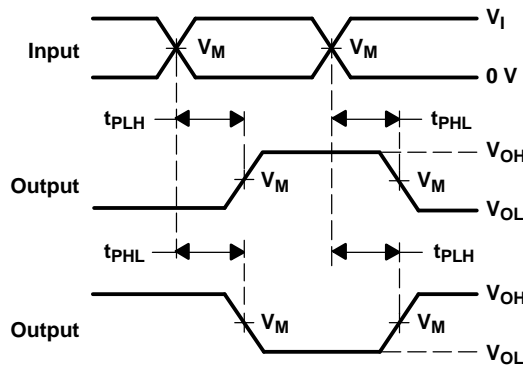
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
     B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.
       Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
     C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz, Z_O = 50 Ω.
     D. The outputs are measured one at a time, with one transition per measurement.
     E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
     F. t_{PZL} and t_{PZH} are the same as t_{en}.
     G. t_{PLH} and t_{PHL} are the same as t_{pd}.
     H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
74LVCH16374ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCH16374ADGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCH16374ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCH16374ADLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16374ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16374ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16374ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16374ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16374AGQLR	ACTIVE	BGA MICROSTAR JUNIOR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LVCH16374AZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
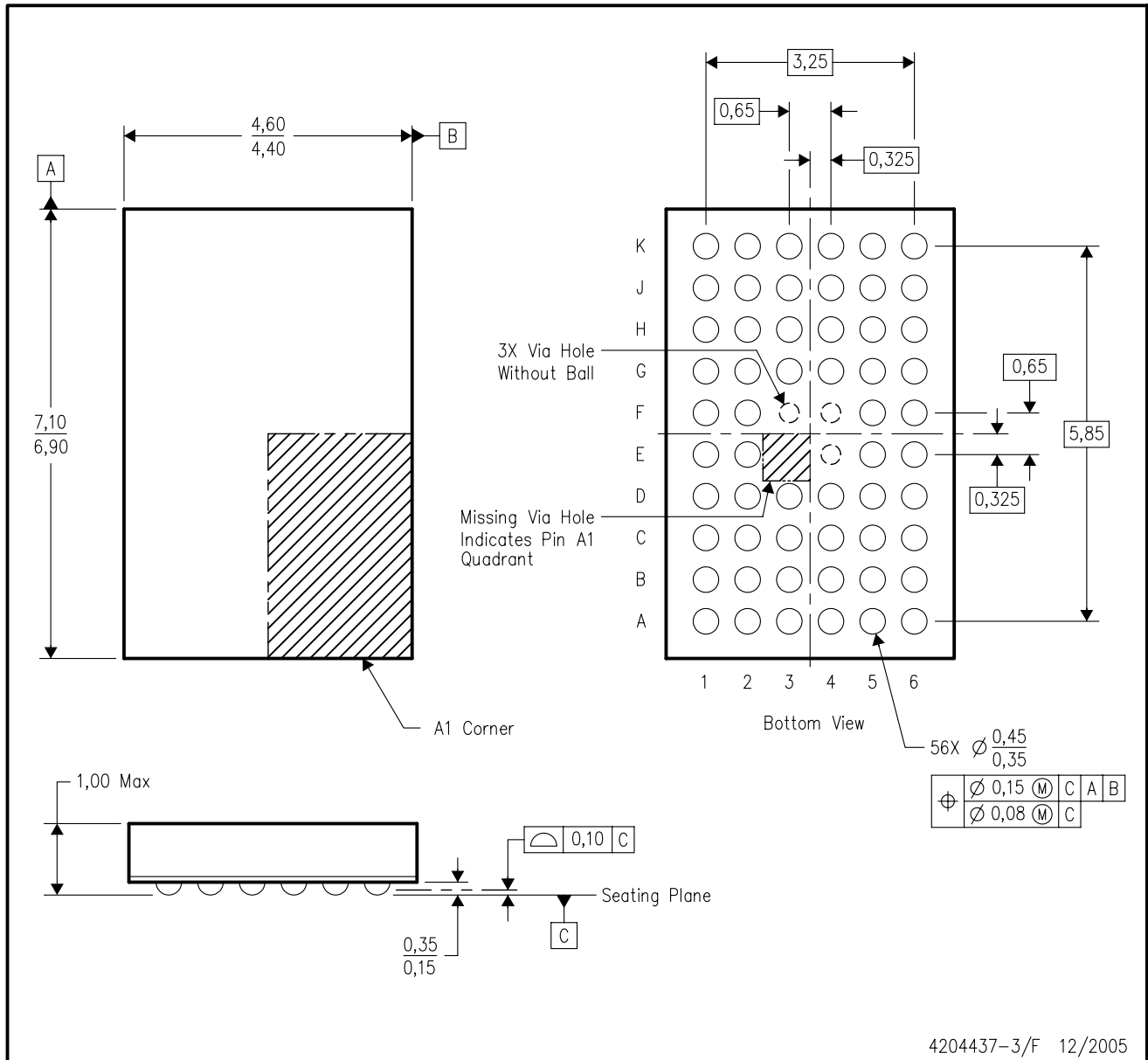
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ZQL (R−PBGA−N56)   PLASTIC BALL GRID ARRAY

3,25

4,60
4,40

0,65

0,325

A

7,10
6,90

B

K
J
H
G
F
E
D
C
B
A

3X Via Hole
Without Ball

0,65

5,85

0,325

Missing Via Hole
Indicates Pin A1
Quadrant

1 2 3 4 5 6

Bottom View

A1 Corner

56X Ø $\frac{0,45}{0,35}$

⊕	Ø 0,15 Ⓜ	C	A	B
	Ø 0,08 Ⓜ	C		

1,00 Max

0,10 C

Seating Plane

0,35
0,15

C

4204437−3/F   12/2005

NOTES: A.   All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
          B.   This drawing is subject to change without notice.
          C.   Falls within JEDEC MO−225 variation BA.
          D.   This package is lead−free. Refer to the 56 GQL package (drawing 4200583) for tin−lead (SnPb).

DGV (R-PDSO-G**)　　　　　　　　　　　　　　　　　　　　　**PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

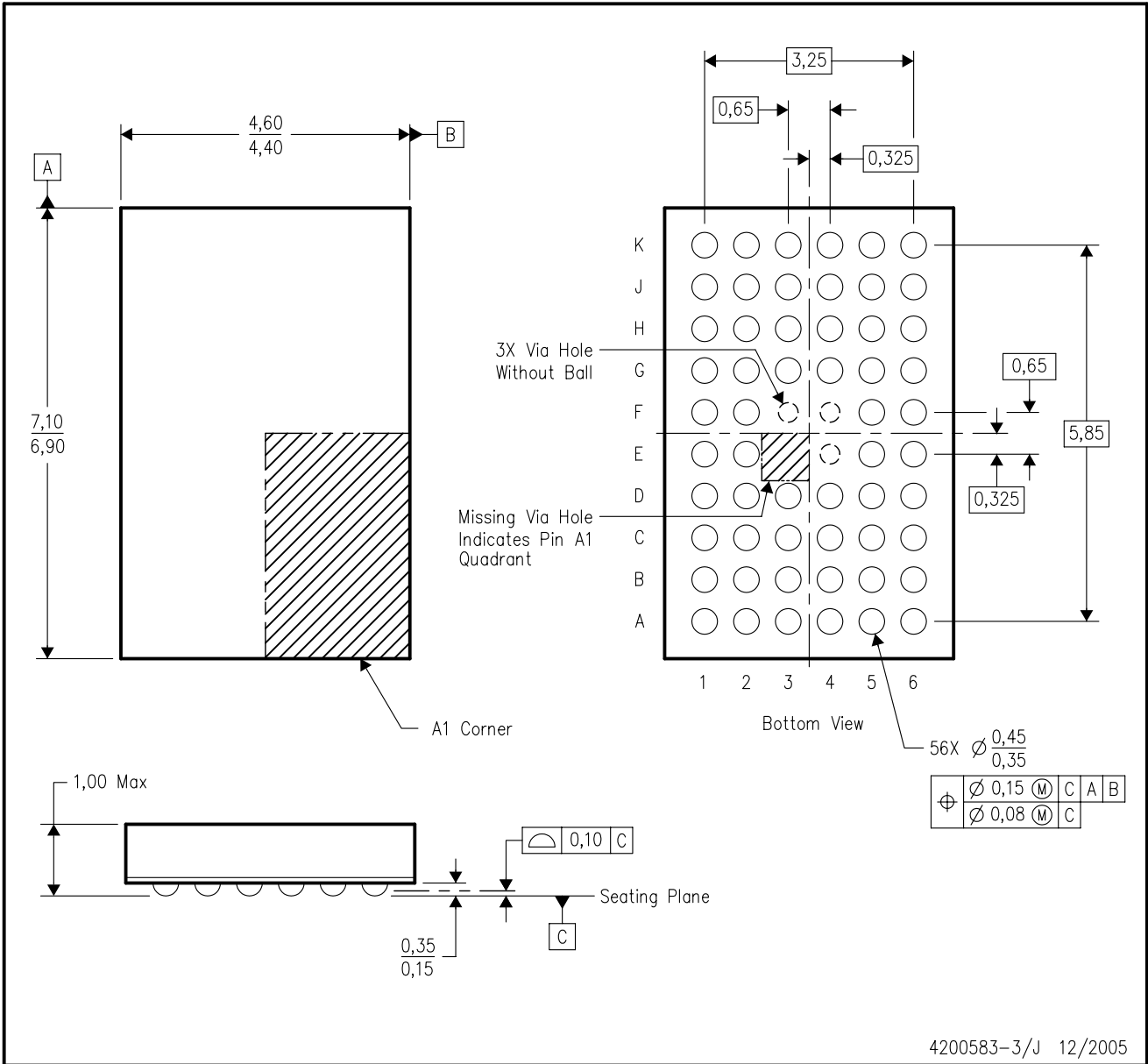| PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
　　　　B. This drawing is subject to change without notice.
　　　　C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
　　　　D. Falls within JEDEC: 24/48 Pins – MO-153
　　　　　　　　　　　　　　14/16/20/56 Pins – MO-194

GQL (R−PBGA−N56)   PLASTIC BALL GRID ARRAY

3,25

0,65

0,325

4,60
4,40   B

A

7,10
6,90

K
J
H
G
F   3X Via Hole
           Without Ball
E
D
C   Missing Via Hole
B   Indicates Pin A1
A   Quadrant

1 2 3 4 5 6

Bottom View

0,65

5,85

0,325

56X Ø 0,45
        0,35

A1 Corner

Ø 0,15 Ⓜ C A B
Ø 0,08 Ⓜ C

1,00 Max

0,10 C

Seating Plane

0,35
0,15

C

4200583−3/J 12/2005
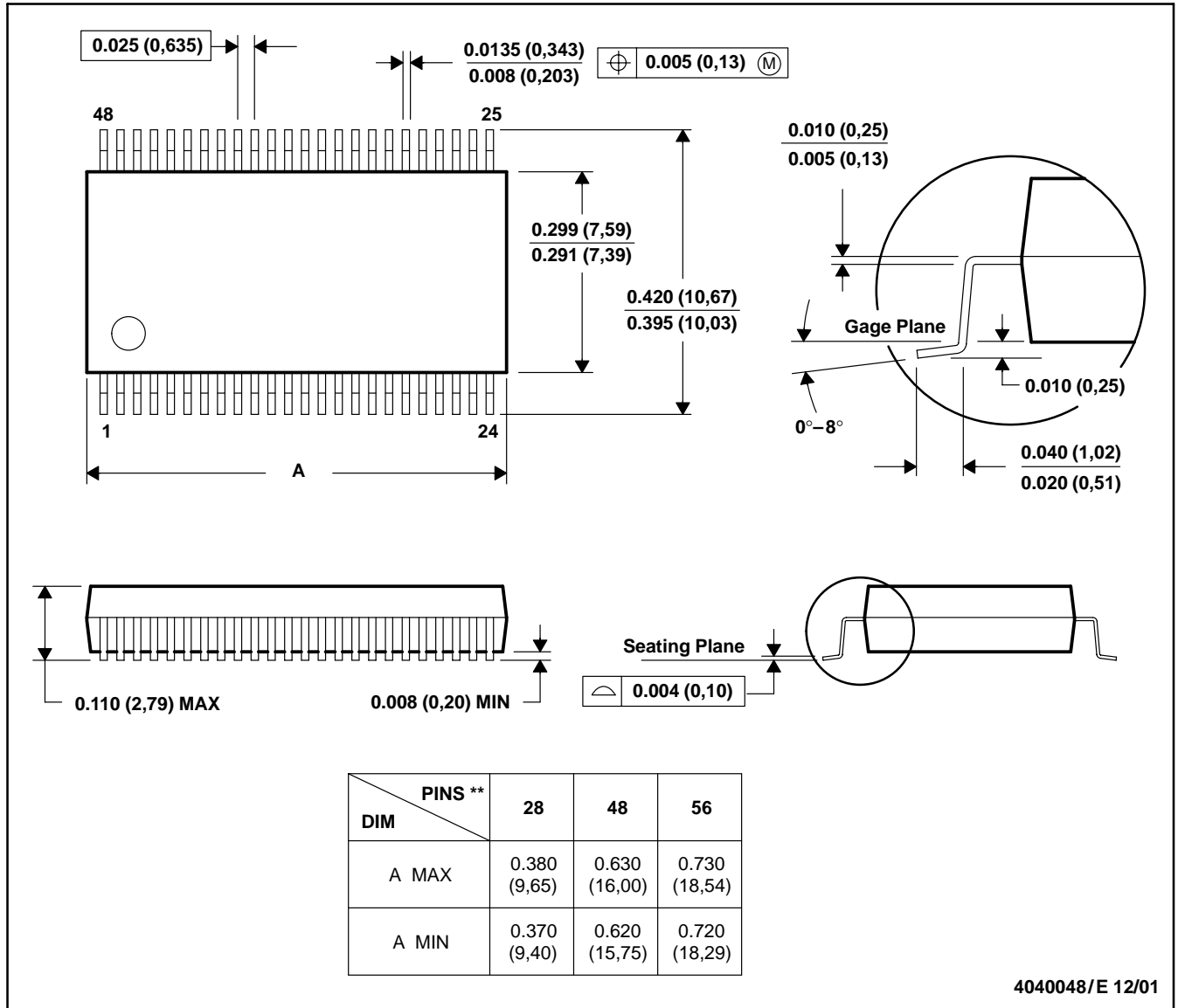
NOTES: A.   All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         C.   Falls within JEDEC MO−225 variation BA.
         D.   This package is tin−lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead−free.

MECHANICAL DATA

MSSO001C – JANUARY 1995 – REVISED DECEMBER 2001

DL (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048/E 12/01

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

4040078/ F 12/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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